

TP250 Series Thermally Conductive Gap Filler

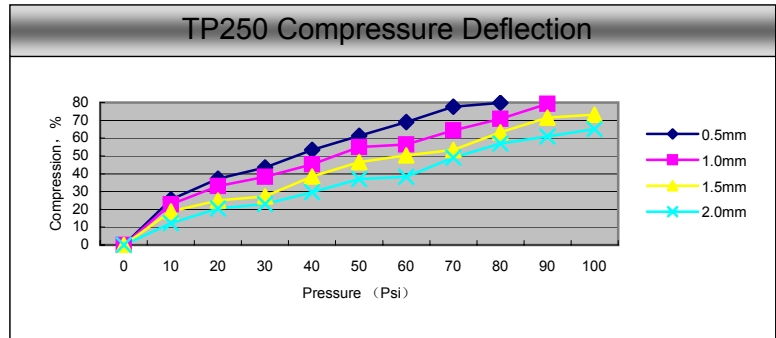
Thermal Interface Materials

Features:

- High thermal conductivity
- High conformability and Low Hardness
- Naturally tacky
- Electrically insulating

Applications:

- Between electronic components such as Semiconductor, IC, CPU.MOS and heatsink.
- Led Lighting, LCD TV, Telecom device, wireless Hub,NB, PC, power supply etc
- Cooling Module, Thermal module, in all applications where a metal housing is used as heatsink.



Typical Properties of TP250			
Properties	Units	Metric Value	Test Method
Construction & Composition	----	Silicone & Ceramic filled	----
Color	----	Light Yellow	Visual
Thickness Range	mm	0.5~5.0	----
Hardness	Shore C	25	ASTM D2240
Density	g/cc	2.93	ASTM D792
Tensile Strength	KN/m	0.4	ASTM D412
Elongation	%	72%	ASTM D412
Continuous Use Temp	°C	-40 to 150	EN344
Breakdown Voltage	Kv/mm	≥5.0	ASTM D149
Volume Impedance	ohm-cm	3.2*10 ¹⁶	ASTM D257
Dielectric Constant	1MHz	6.3	ASTM D150
Weight Damnify	----	≤0.5%	@150°C 240H
Flame Rating	----	V-0	UL 94
Thermal Conductivity	W/m.k	2.5	ASTM E1461
UL, RoHS, REACH	----	Compliance	----

Sheet sizes:

Standard sheet size:200x400mm,330x330mm; Custom Die-cut parts available; Available with or without PSA

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